

FLEX STACK

MICRO BOARD STACKER

(1.27 mm) .050" PITCH • FW SERIES

4
Gbps



FW

Board Mates:

CLP, FLE

Cable Mates:

FFSD

SPECIFICATIONS

Insulator Material:

Black Liquid Crystal Polymer

Terminal Material:

Phosphor Bronze

Plating:

Sn or Au over 50 μ" (1.27 μm) Ni

Operating Temp Range:

-55 °C to +125 °C

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (02-30)

(0.15 mm) .006" max (31-50)*

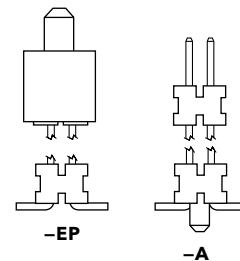
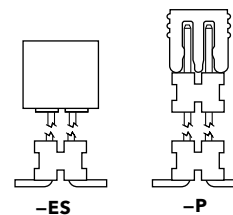
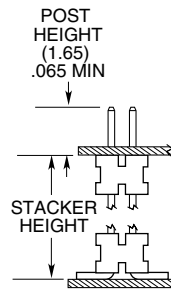
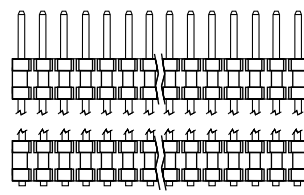
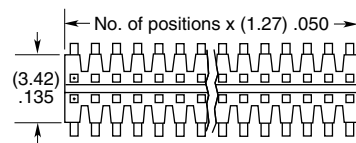
*(.004" stencil solution may be available; contact ipg@samtec.com)

MATED HEIGHT

FW LEAD STYLE	CLP LEAD STYLE	MATED HEIGHT*
FW-XX-03-X-X-233-065	-02	(8.13 mm) .320"
FW-XX-03-X-X-303-065		(9.91 mm) .390"

*Processing conditions will affect mated height.

SURFACE MOUNT

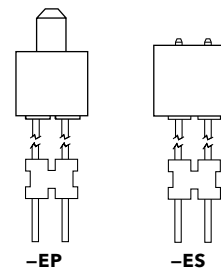
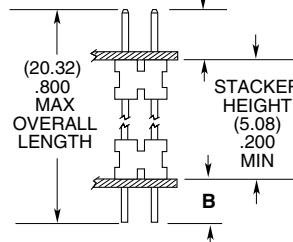
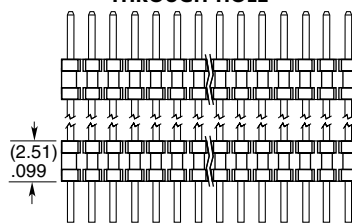


ALSO AVAILABLE

Contact Samtec

Smaller stack heights

THROUGH-HOLE



LEAD STYLE	TAIL (B)
-01	(1.14) .045
-02	(1.91) .075
-04	(2.29) .090

Notes:

For added mechanical stability, Samtec recommends mechanical board spacers be used in applications with gold or selective gold plated connectors. Contact ipg@samtec.com for more information.

This Series is non-standard, non-returnable.

samtec.com?FW-SM or samtec.com?FW-TH

F-226 (Rev 09 DEC25)

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.